


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/23/14272	
1.3 Title of PCN	ST Muar (Malaysia) qualification of extra large strip size for substrate for TFBGA 5x5 package assembly line - for STM32L0x/L1x and STM32F1x listed products	
1.4 Product Category	STM32Lx STM32Fx	
1.5 Issue date	2023-12-27	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	NEMETH KRISZTINA
2.1.2 Phone	+49 89460062210
2.1.3 Email	krisztina.nemeth@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	Any change on substrate (part number, supplier, plant, design or composition of any layer, etc..)	ST MUAR (Malaysia)

4. Description of change

	Old	New
4.1 Description	The current Bill of Materials in ST Muar (Malaysia) assembly plant is described in Additional information document.	ST Muar (Malaysia) assembly plant 1. New Bonder platform upgraded to state of the art equipment. 2. New product Bill of Materials : - BOM items have been rationalized. - Solder mask was upgraded to halogen free composition. - Substrate strip size moved from Matrix to Extra-Large density. See detailed description in Additional information document.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	NO CHANGE - Same Form, Fit, Function	

5. Reason / motivation for change

5.1 Motivation	EHS Standard will be upgraded - new BOM is greener (BPA free)
5.2 Customer Benefit	ENVIRONMENT FOOTPRINT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensure by ST internal tools
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7. Timing / schedule

7.1 Date of qualification results	2024-05-01
7.2 Intended start of delivery	2024-05-20
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	14272 MDG-GPM-RER2333 PCN14272 ST Muar XL strip size for substrate for TFBGA 5x5 package - plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2023-12-27

9. Attachments (additional documentations)

14272 Public product.pdf
14272 MDG-GPM-RER2333 PCN14272 ST Muar XL strip size for substrate for TFBGA 5x5 package - plan.pdf
14272 PCN14272_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32L151R8H6	

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